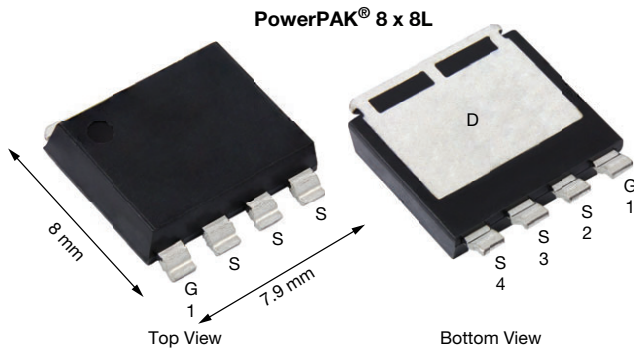


# Automotive N-Channel 60 V (D-S) 175 °C MOSFET

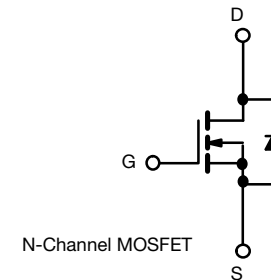


**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**



## FEATURES

- TrenchFET® Gen IV power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>g</sub> and UIS tested
- Thin 1.6 mm height
- Material categorization:  
for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



PRODUCT SUMMARY	
V <sub>DS</sub> (V)	60
R <sub>DS(on)</sub> (Ω) at V <sub>GS</sub> = 4.5 V	0.0011
R <sub>DS(on)</sub> (Ω) at V <sub>GS</sub> = 10 V	0.00080
I <sub>D</sub> (A) <sup>e</sup>	461
Configuration	Single

ORDERING INFORMATION	
Package	PowerPAK 8 x 8L
Lead (Pb)-free and halogen-free	SQJQ160EL (for detailed order number please see <a href="http://www.vishay.com/doc?79776">www.vishay.com/doc?79776</a> )

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-source voltage	V <sub>DS</sub>	60	V		
Gate-source voltage	V <sub>GS</sub>	± 20			
Continuous drain current <sup>e</sup>	I <sub>D</sub>	T <sub>C</sub> = 25 °C	461	A	
		T <sub>C</sub> = 125 °C	266		
Continuous source current (diode conduction)	I <sub>S</sub>	317	mJ		
Pulsed drain current <sup>a, e</sup>	I <sub>DM</sub>	655			
Single pulse avalanche current	I <sub>AS</sub>	L = 0.1 mH	69	W	
Single pulse avalanche energy			E <sub>AS</sub>		238
Maximum power dissipation <sup>e</sup>	P <sub>D</sub>	T <sub>C</sub> = 25 °C	348	°C	
		T <sub>C</sub> = 125 °C	116		
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C		
Soldering recommendations (peak temperature) <sup>c</sup>		260			

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-ambient	R <sub>thJA</sub>	44	°C/W	
Junction-to-case (drain) <sup>d</sup>	R <sub>thJC</sub>	0.43		

### Notes

- Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2 %
- When mounted on 1" square PCB (FR4 material)
- See solder profile ([www.vishay.com/doc?73257](http://www.vishay.com/doc?73257))
- As per JESD51-14
- Values based on R<sub>thJC</sub> and T<sub>C</sub> of 25 °C- Actual values achievable will be dependent on the thermal characteristics of the complete system



<b>SPECIFICATIONS</b> ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
<b>Static</b>							
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0, I_D = 250\text{ }\mu\text{A}$		60	-	-	V
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		1.5	2.0	2.5	
Gate-source leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$		-	-	$\pm 100$	nA
Zero gate voltage drain current	$I_{DSS}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}$	-	-	1	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}, T_J = 125\text{ }^\circ\text{C}$	-	-	50	
		$V_{GS} = 0\text{ V}$	$V_{DS} = 60\text{ V}, T_J = 175\text{ }^\circ\text{C}$	-	-	500	
On-state drain current <sup>a</sup>	$I_{D(on)}$	$V_{GS} = 10\text{ V}$	$V_{DS} \geq 5\text{ V}$	50	-	-	A
Drain-source on-state resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}$	$I_D = 20\text{ A}$	-	0.00090	0.0011	$\Omega$
		$V_{GS} = 10\text{ V}$	$I_D = 20\text{ A}$	-	0.00056	0.00080	
		$V_{GS} = 10\text{ V}$	$I_D = 20\text{ A}, T_J = 125\text{ }^\circ\text{C}$	-	-	0.0014	
		$V_{GS} = 10\text{ V}$	$I_D = 20\text{ A}, T_J = 175\text{ }^\circ\text{C}$	-	-	0.0017	
Forward transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15\text{ V}, I_D = 40\text{ A}$		-	205	-	S
<b>Dynamic <sup>b</sup></b>							
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{ V}$	$V_{DS} = 25\text{ V}, f = 1\text{ MHz}$	-	13 236	18 531	$\mu\text{F}$
Output capacitance	$C_{oss}$			-	4447	6226	
Reverse transfer capacitance	$C_{rss}$			-	219	307	
Total gate charge <sup>c</sup>	$Q_g$	$V_{GS} = 10\text{ V}$	$V_{DS} = 30\text{ V}, I_D = 50\text{ A}$	-	206	309	nC
Gate-source charge <sup>c</sup>	$Q_{gs}$			-	42	-	
Gate-drain charge <sup>c</sup>	$Q_{gd}$			-	31	-	
Gate resistance	$R_g$	f = 1 MHz		0.4	1.6	3.2	$\Omega$
Turn-on delay time <sup>c</sup>	$t_{d(on)}$	$V_{DD} = 30\text{ V}, R_L = 0.6\text{ }\Omega,$ $I_D \equiv 50\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$		-	17	26	ns
Rise time <sup>c</sup>	$t_r$			-	13	20	
Turn-off delay time <sup>c</sup>	$t_{d(off)}$			-	82	123	
Fall time <sup>c</sup>	$t_f$			-	20	30	
<b>Source-Drain Diode Ratings and Characteristics <sup>b</sup></b>							
Pulsed current <sup>a</sup>	$I_{SM}$			-	-	655	A
Forward voltage	$V_{SD}$	$I_F = 40\text{ A}, V_{GS} = 0\text{ V}$		-	0.7	1.1	V
Body diode reverse recovery time	$t_{rr}$	$I_F = 50\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$		-	86	172	ns
Body diode reverse recovery charge	$Q_{rr}$			-	174	348	nC
Reverse recovery fall time	$t_a$			-	50	-	ns
Reverse recovery rise time	$t_b$			-	37	-	
Body diode peak reverse recovery current	$I_{RM(REC)}$					-	3.5

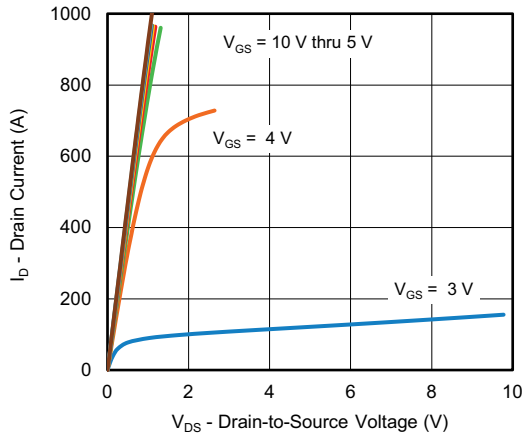
**Notes**

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

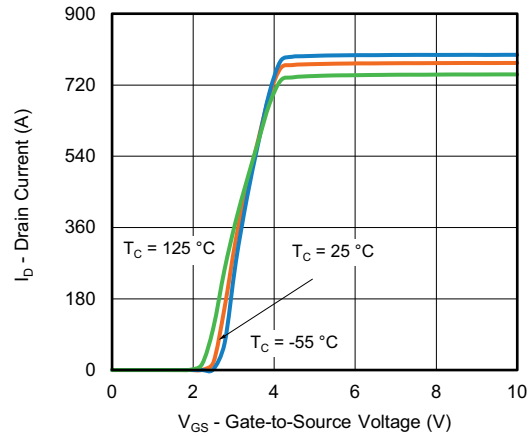
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



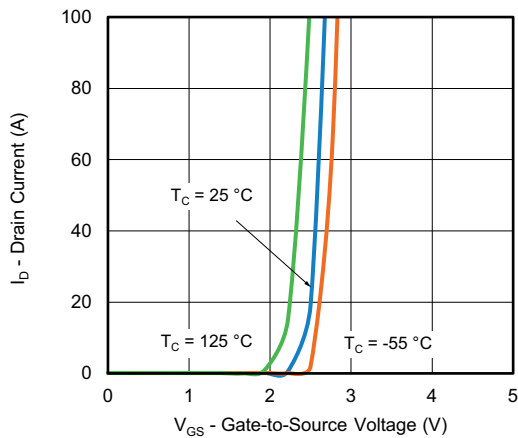
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



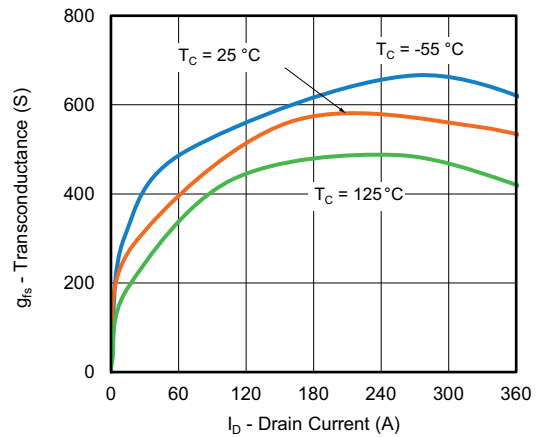
Output Characteristics



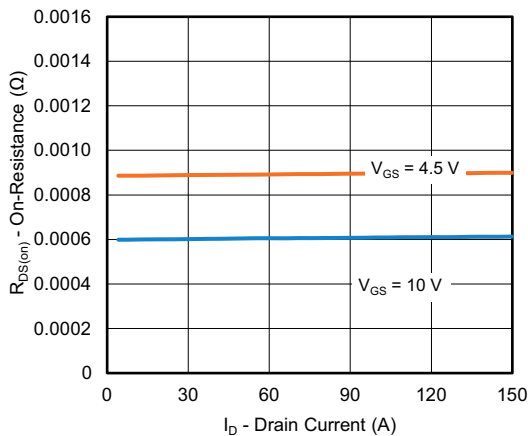
Transfer Characteristics



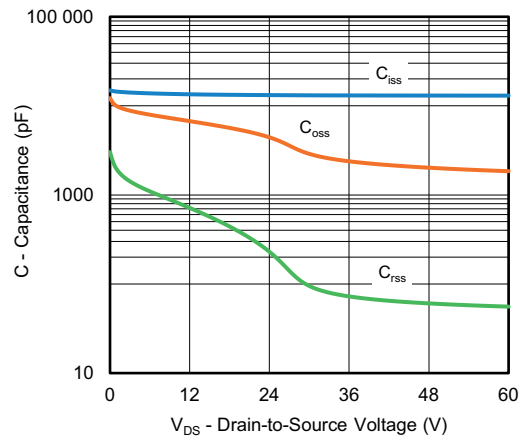
Transfer Characteristics



Transconductance



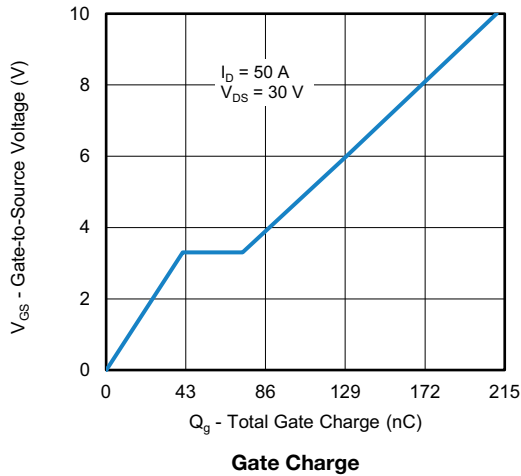
On-Resistance vs. Drain Current



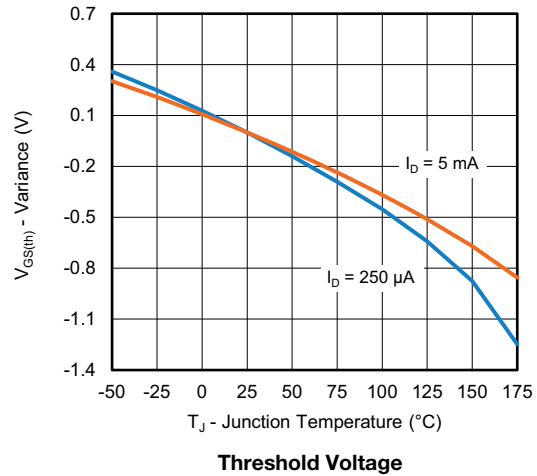
Capacitance



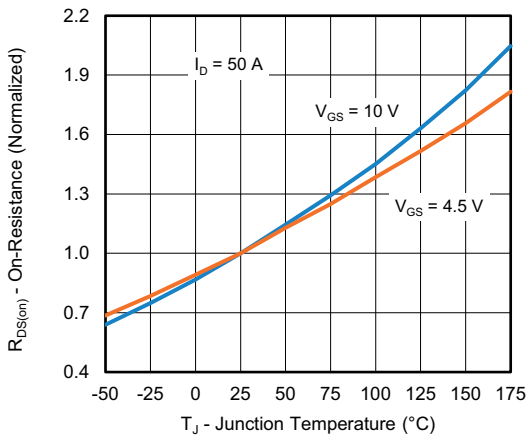
TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



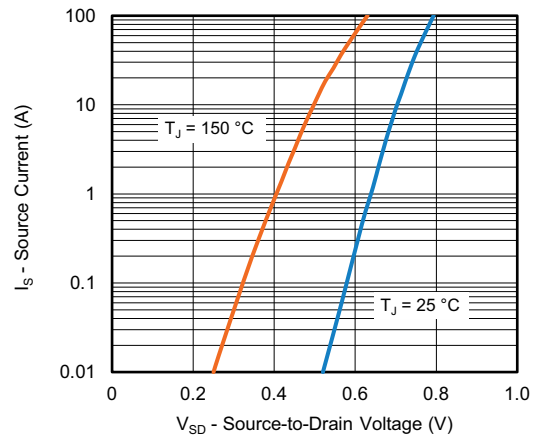
Gate Charge



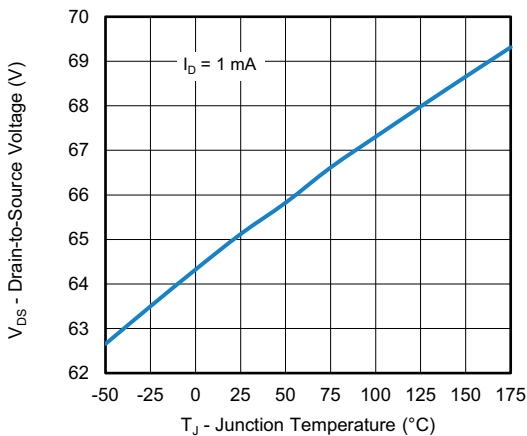
Threshold Voltage



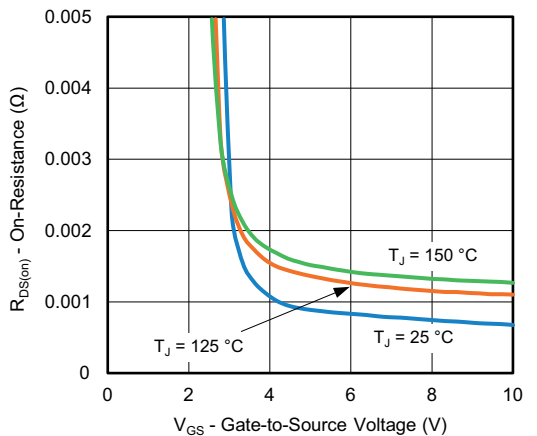
On-Resistance vs. Junction Temperature



Source Drain Diode Forward Voltage



Drain Source Breakdown vs. Junction Temperature



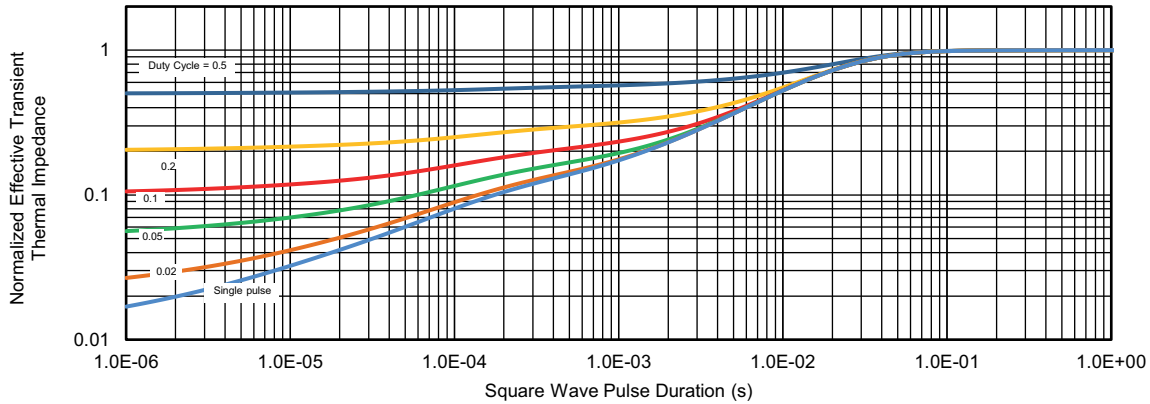
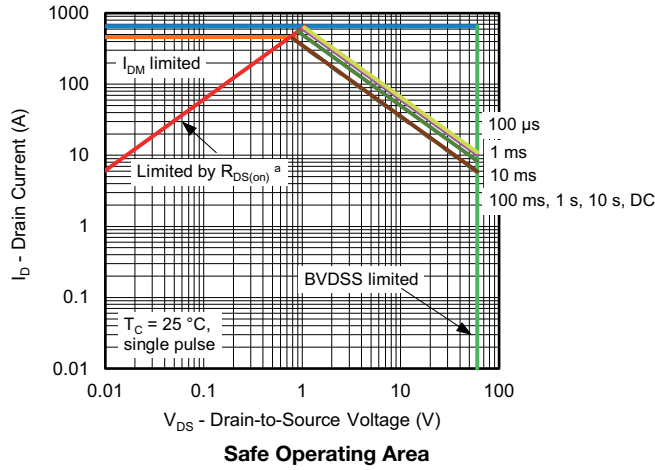
On-Resistance vs. Gate-to-Source Voltage

Note

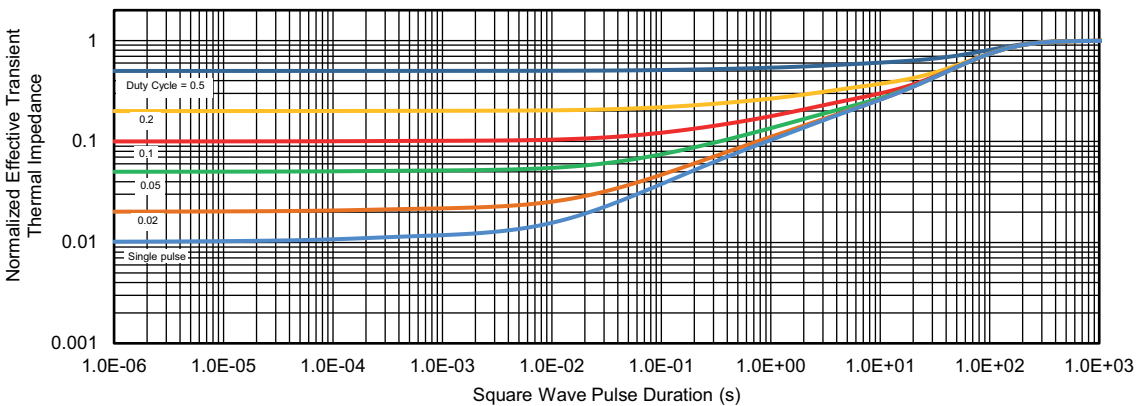
- a. V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified



**THERMAL RATINGS** ( $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Case**



**Normalized Thermal Transient Impedance, Junction-to-Ambient**

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